



**THE DATASHEET OF
MC74AC157DR2**



Quad 2-Input Multiplexer

MC74AC157, MC74ACT157

The MC74AC157/74ACT157 is a high-speed quad 2-input multiplexer. Four bits of data from two sources can be selected using the common Select and Enable inputs. The four outputs present the selected data in the true (non-inverted) form.

The MC74AC157/74ACT157 can also be used as a function generator.

Features

- Outputs Source/Sink 24 mA
- 'ACT157 Has TTL Compatible Inputs
- These are Pb-Free Devices

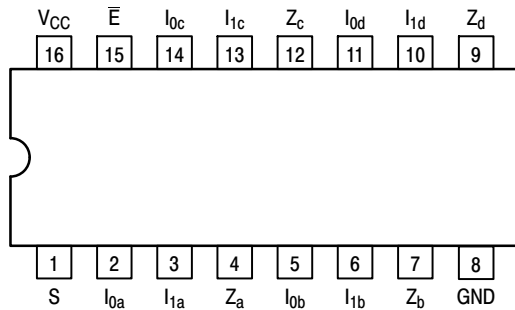


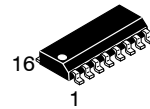
Figure 1. Pinout: 16-Lead Packages Conductors (Top View)

TRUTH TABLE

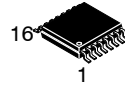
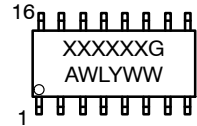
Inputs				Outputs
E-bar	S	I ₀	I ₁	Z
H	X	X	X	L
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

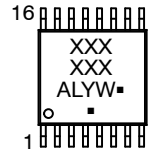
MARKING DIAGRAMS



SOIC-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F



XXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN NAMES

PIN	FUNCTION
I _{0a} -I _{0d}	Source 0 Data Inputs
I _{1a} -I _{1d}	Source 1 Data Inputs
E-bar	Enable Input
S	Select Input
Z _a -Z _d	Outputs

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MC74AC157, MC74ACT157

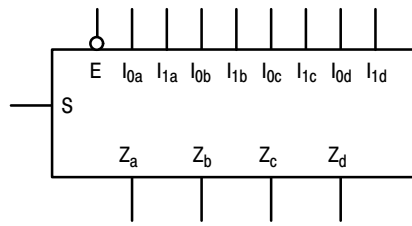


Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC157/74ACT157 is a quad 2-input multiplexer. It selects four bits of data from two sources under the control of a common Select input (S). The Enable input (\bar{E}) is active-LOW. When \bar{E} is HIGH, all of the outputs (Z) are forced LOW regardless of all other inputs. The MC74AC157/74ACT157 is the logic implementation of a 4-pole, 2-position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

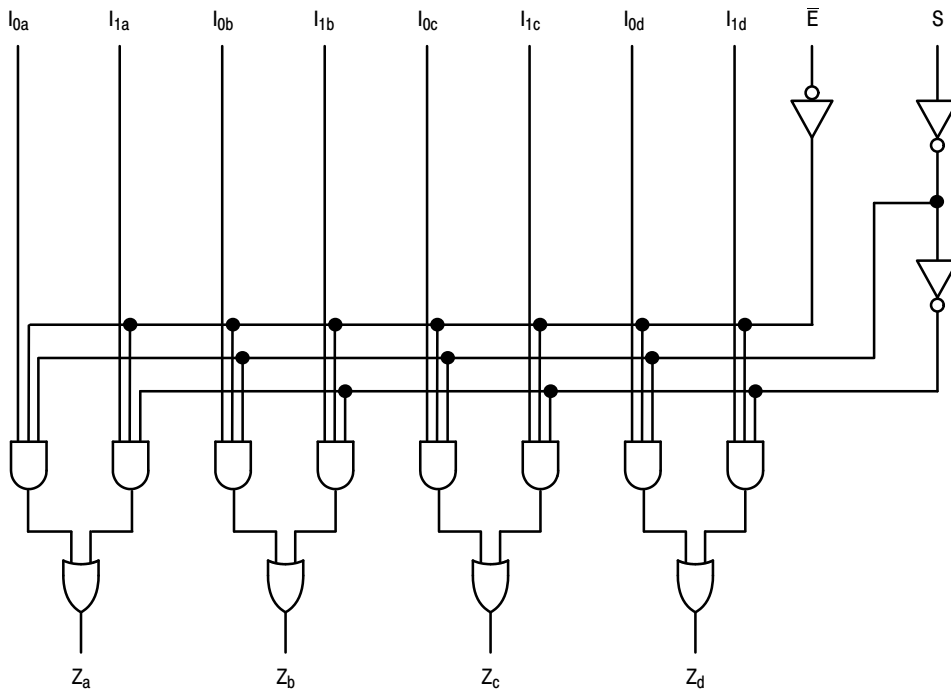
$$Z_a = \bar{E} \cdot (I_{1a} \cdot S + I_{0a} \cdot \bar{S})$$

$$Z_b = \bar{E} \cdot (I_{1b} \cdot S + I_{0b} \cdot \bar{S})$$

$$Z_c = \bar{E} \cdot (I_{1c} \cdot S + I_{0c} \cdot \bar{S})$$

$$Z_d = \bar{E} \cdot (I_{1d} \cdot S + I_{0d} \cdot \bar{S})$$

A common use of the MC74AC157/74ACT157 is the moving of data from two groups of registers to four common output busses. The particular register from which the data comes is determined by the state of the Select input. A less obvious use is as a function generator. The MC74AC157/74ACT157 can generate any four of the sixteen different functions of two variables with one variable common. This is useful for implementing gating functions.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MC74AC157, MC74ACT157

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +6.5	V
V _I	DC Input Voltage	-0.5 ≤ V _I ≤ V _{CC} + 0.5	V
V _O	DC Output Voltage (Note 1)	-0.5 ≤ V _O ≤ V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	±20	mA
I _{OK}	DC Output Diode Current	±50	mA
I _O	DC Output Sink/Source Current	±50	mA
I _{CC}	DC Supply Current per Output Pin	±50	mA
I _{GND}	DC Ground Current per Output Pin	±50	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction temperature under Bias	+150	°C
θ _{JA}	Thermal Resistance (Note 2)	SOIC TSSOP 126 159	°C/W
P _D	Power Dissipation in Still Air at 25°C (Note 3)	SOIC TSSOP 995 787	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating	Oxygen Index: 30% – 35% UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 4) Charged Device Model (Note 5) > 2000 > 1000	V
I _{Latch-Up}	Latch-Up Performance	Above V _{CC} and Below GND at 85°C (Note 6)	±100 mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JESD51-7.
3. 500 mW at 65°C; derate to 300 mW by 10 mW/ from 65°C to 85°C.
4. Tested to EIA/JESD22-A114-A.
5. Tested to JESD22-C101-A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V _{CC}	Supply Voltage	'AC	2.0	5.0	6.0	V
		'ACT	4.5	5.0	5.5	
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)	0	-	V _{CC}	V	
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	-	150	-	ns/V
		V _{CC} @ 4.5 V	-	40	-	
		V _{CC} @ 5.5 V	-	25	-	
t _r , t _f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	10	-	ns/V
		V _{CC} @ 5.5 V	-	8.0	-	
T _A	Operating Ambient Temperature Range	-40	25	85	°C	
I _{OH}	Output Current – High	-	-	-24	mA	
I _{OL}	Output Current – Low	-	-	24	mA	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

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DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC		Unit	Conditions					
			T _A = +25°C		T _A = -40°C to +85°C								
			Typ	Guaranteed Limits									
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V					
		4.5	2.25	3.15	3.15								
		5.5	2.75	3.85	3.85								
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V					
		4.5	2.25	1.35	1.35								
		5.5	2.75	1.65	1.65								
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9		V	I _{OUT} = -50 μA					
		4.5	4.49	4.4	4.4								
		5.5	5.49	5.4	5.4								
	3.0	-	2.56	2.46		V	*V _{IN} = V _{IL} or V _{IH} -12 mA						
								4.5	-	3.86	3.76		
													5.5
I _{OH}	-24 mA	-24 mA	-24 mA										
					V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1		V	I _{OUT} = 50 μA
							4.5	0.001	0.1	0.1			
5.5	0.001	0.1	0.1										
3.0	-	0.36	0.44		V	*V _{IN} = V _{IL} or V _{IH} 12 mA							
							4.5	-	0.36	0.44			
												5.5	-
I _{OL}	24 mA	24 mA	24 mA										
					I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0		μA	V _I = V _{CC} , GND
					I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75		mA	V _{OLD} = 1.65 V Max
I _{OHD}	5.5	-	-	-75			mA	V _{OHD} = 3.85 V Min					
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80		μA	V _{IN} = V _{CC} or GND					

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		
			Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay S to Z _n	3.3	1.5	7.0	11.5	1.5	13.0	ns
		5.0	1.5	5.5	9.0	1.5	10.0	
t _{PHL}	Propagation Delay S to Z _n	3.3	1.5	6.5	11.0	1.5	12.0	ns
		5.0	1.5	5.0	8.5	1.0	9.5	
t _{PLH}	Propagation Delay E to Z _n	3.3	1.5	7.0	11.5	1.5	13.0	ns
		5.0	1.5	5.5	9.0	1.5	10.0	
t _{PHL}	Propagation Delay E _n to Z _n	3.3	1.5	6.5	11.0	1.5	12	ns
		5.0	1.5	5.5	9.0	1.0	9.5	
t _{PLH}	Propagation Delay I _n to Z _n	3.3	1.5	5.0	8.5	1.0	9.0	ns
		5.0	1.5	4.0	6.5	1.0	7.0	
t _{PHL}	Propagation Delay I _n to Z _n	3.3	1.5	5.0	8.0	1.0	9.0	ns
		5.0	1.5	4.0	6.5	1.0	7.0	

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

MC74AC157, MC74ACT157

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	4.5	1.5	2.0	2.0	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		5.5	1.5	2.0	2.0			
V _{IL}	Maximum Low Level Input Voltage	4.5	1.5	0.8	0.8	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
		5.5	1.5	0.8	0.8			
V _{OH}	Minimum High Level Output Voltage	4.5	4.49	4.4	4.4	V	I _{OUT} = -50 μA	
		5.5	5.49	5.4	5.4			
		4.5	-	3.86	3.76	V	*V _{IN} = V _{IL} or V _{IH} -24 mA	
		5.5	-	4.86	4.76			
V _{OL}	Maximum Low Level Output Voltage	4.5	0.001	0.1	0.1	V	I _{OUT} = 50 μA	
		5.5	0.001	0.1	0.1			
		4.5	-	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA	
		5.5	-	0.36	0.44			
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND	
ΔI _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5	mA	V _I = V _{CC} - 2.1 V	
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μA	V _{IN} = V _{CC} or GND	

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		
			Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay S to Z _n	5.0	2.0	-	9.0	1.5	10.0	ns
t _{PHL}	Propagation Delay S to Z _n	5.0	2.0	-	9.5	2.0	10.5	ns
t _{PLH}	Propagation Delay E _n to Z _n	5.0	1.5	-	10	1.5	11.5	ns
t _{PHL}	Propagation Delay E _n to Z _n	5.0	1.5	-	8.5	1.0	9.0	ns
t _{PLH}	Propagation Delay I _n to Z _n	5.0	1.5	-	7.0	1.0	8.5	ns
t _{PHL}	Propagation Delay I _n to Z _n	5.0	1.5	-	7.5	1.0	8.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value - Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	50	pF	V _{CC} = 5.0 V

MC74AC157, MC74ACT157

ORDERING INFORMATION

Device Order Number	Marking	Package	Shipping [†]
MC74AC157DG	AC157	SOIC-16 (Pb-Free)	48 Units / Rail
MC74AC157DR2G	AC157	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74AC157DR2G-Q*	AC157	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74AC157DTR2G	AC 157	TSSOP-16 (Pb-Free)	2500 Tape & Reel
MC74ACT157DG	ACT157	SOIC-16 (Pb-Free)	48 Units / Rail
MC74ACT157DR2G	ACT157	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74ACT157DTR2G	ACT 157	TSSOP-16 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOIC-16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.00	0.05	0.10
A2	1.35	1.50	1.65
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D

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DESCRIPTION:	SOIC-16 9.90X3.90X1.50 1.27P	PAGE 1 OF 2

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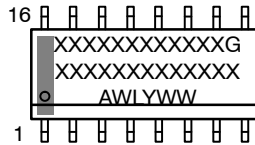
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SOIC-16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

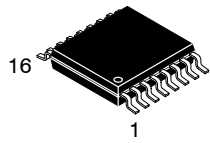
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

<p>STYLE 1:</p> <p>PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR</p>	<p>STYLE 2:</p> <p>PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE</p>	<p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4</p>	<p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1</p>
<p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1</p>	<p>STYLE 6:</p> <p>PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE</p>	<p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH</p>	

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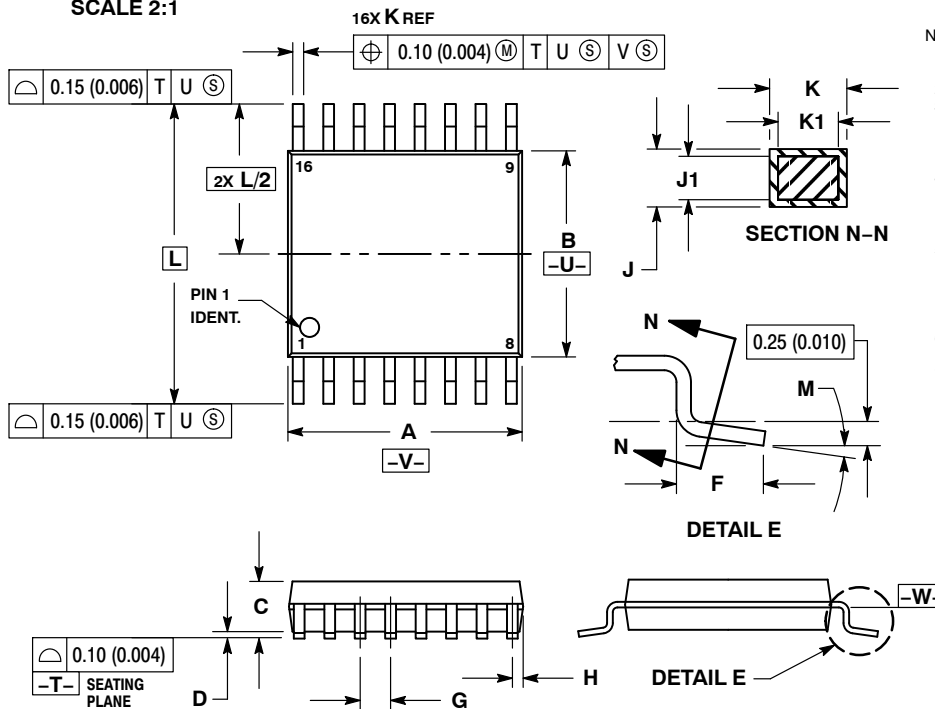
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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006

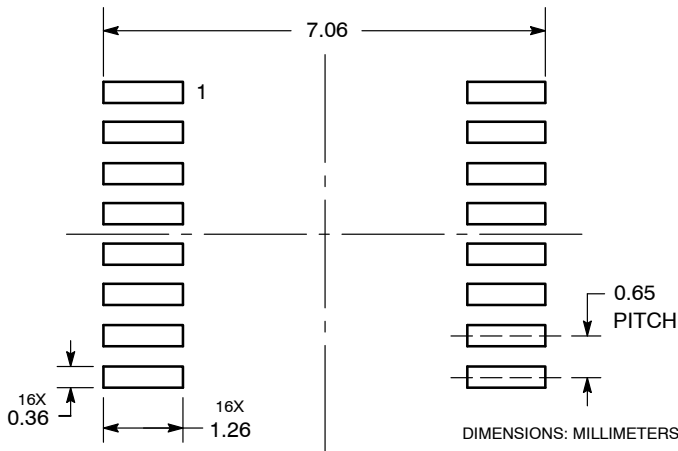


NOTES:

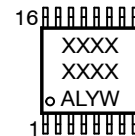
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED
SOLDERING FOOTPRINT***



**GENERIC
MARKING DIAGRAM***



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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